

Form Type	Distribute	Version	2.0	Ref	IPO	C 1752A	Sectional	s Material Info	o Subsectiona	als D, A	
		1			plier Infor		1222			-1-,	
Company Name	TE Connecti	vity Request Document I	D		Contact Name		id Benfer	Contact Title	Product Complia	nce Engineer	
Company Unique ID	TE Connecti			11 C	Contact Email d		e.benfer@te.c	om			
Contact Phone	Number	717-986-372	25	•		•					
				L	egal State	ment					
Supplier Acceptance	true										
Legal Statemen	t										
		document is base pecifications or exi									
		1			Produc	t		T	1		
Manufacturer Item number	1-1337445-0		4452.8		ersion	-		Identity			
Manufacturer Item Name	BNC Str PCE 50Ohm Silve	B Skt Weight Uon	n mg	M	fr Site			Authority			
Date		UOM Each									
EURoHS-0508	· · · · ·	Product(s) meets EU RoHS requirements by application of the selected exemption(s) Product(s) is NOT eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information									
ChinaRoHS- 0508	Product(s) is Products	NOT eligible for m	narking with the e	code und	er China's	Measures	tor Administra	tion of the control	or pollution by Ele	ctronic Informatio	
EUREACH-1214	REACH Can	didate Substances	of Very High Co	ncern ARI	NOT Cor	ntained in th	he Product Ab	ove the Limits per	the Definition with	in REACH	
				Pro	duct Disc	losure					
Sub- Item/Material/ Substance	Level	Name	Substance Category	Substan CAS		bstance incentration	Quantity	Mass per U	Jnit UOM	Exemption	
Material	1	COPPER ALLOY_CONT ACT					1.0	250.0	mg		
Substance	2	Tin	Supplier	7440-31-	5 0.4	1	1.0	1.0	mg		
Substance	2	Copper	Supplier	7440-50-	8 58.	.08	1.0	145.2	mg		
Substance	2	Iron	Supplier	7439-89-	6 0.3	32	1.0	0.8	mg		
Substance	2	Zinc	Supplier	7440-66-	6 37.	.87995	1.0	94.69988	mg		
Substance	2	Lead	Lead/Lead Compounds	7439-92-	1 3.3	32	1.0	8.3	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight	
Substance	2	Cadmium	Cadmium/Cad mium Compounds	7440-43-	9 5.0)E-5	1.0	1.25E-4	mg		
Material	1	SLEEVE- SILVER PLATING_SLE EVE					1.0	6.8	mg		
Substance	2	Silver	Supplier	7440-22-	4 100	0.0	1.0	6.8	mg		
Material	1	INSULATION- PTFE_ INSULATION					1.0	370.0	mg		
Substance	2	Ethene, 1,1,2,2- tetrafluoro-, homopolymer	Supplier	9002-84-	0 100	0.0	1.0	370.0	mg		
Material	1	CONTACT- SILVER PLATING_ CONTACT					1.0	8.0	mg		
Substance	2	Silver	Supplier	7440-22-	4 100	0.0	1.0	8.0	mg		
Material	1	COPPER ALLOY_BODY					1.0	3560.0	mg		
	2	Iron	Supplier	7439-89-	6 0.3	32	1.0	11.392	mg		
	2	Zinc	Supplier	7440-66-		.87995	1.0 1348.52		2 mg		
	2	Tin	Supplier	7440-31-			1.0	14.24	mg		
	2	Copper	Supplier	7440-50-		.08	1.0	2067.648	mg		
Substance	2	Cadmium	Cadmium/Cad mium Compounds	7440-43-	9 5.0)E-5	1.0	0.00178	mg		

Substance	2	Lead	Lead/Lead Compounds	7439-92-1	3.32	1.0	118.192	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	COPPER ALLOY SLEEVE- Brass(SPEC.JI S C2680)				1.0	178.0	mg	
Substance	2	Zinc	Supplier	7440-66-6	32.377	1.0	57.63106	mg	
Substance	2	Iron	Supplier	7439-89-6	0.02	1.0	0.0356	mg	
Substance	2	Copper	Supplier	7440-50-8	67.6	1.0	120.328	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.0030	1.0	0.00534	mg	
Material	1	BODY-SILVER PLATING BODY				1.0	80.0	mg	
Substance	2	Silver	Supplier	7440-22-4	100.0	1.0	80.0	mg	